

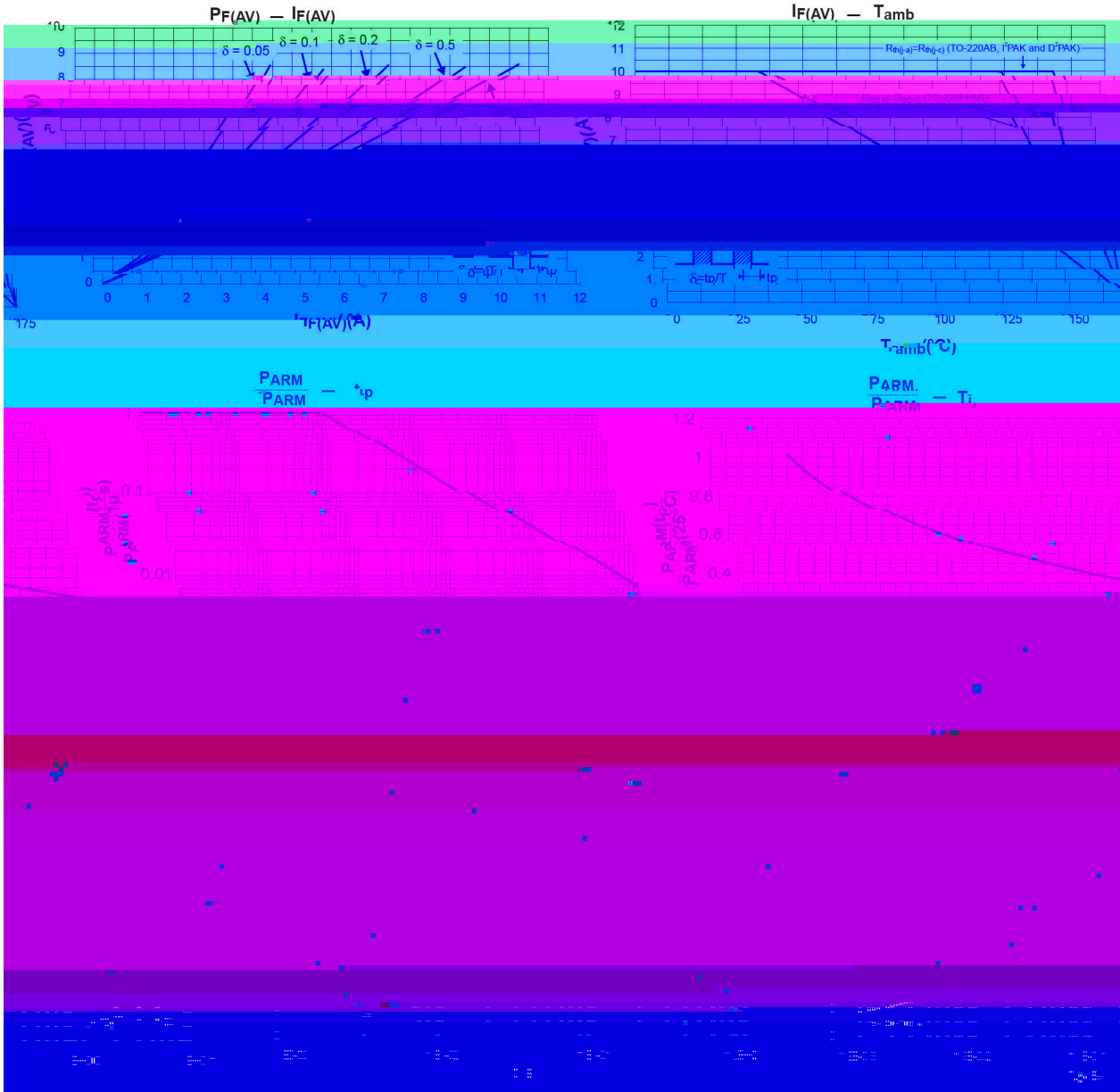
MBRF20150CT

Rev.F Mar.-2016

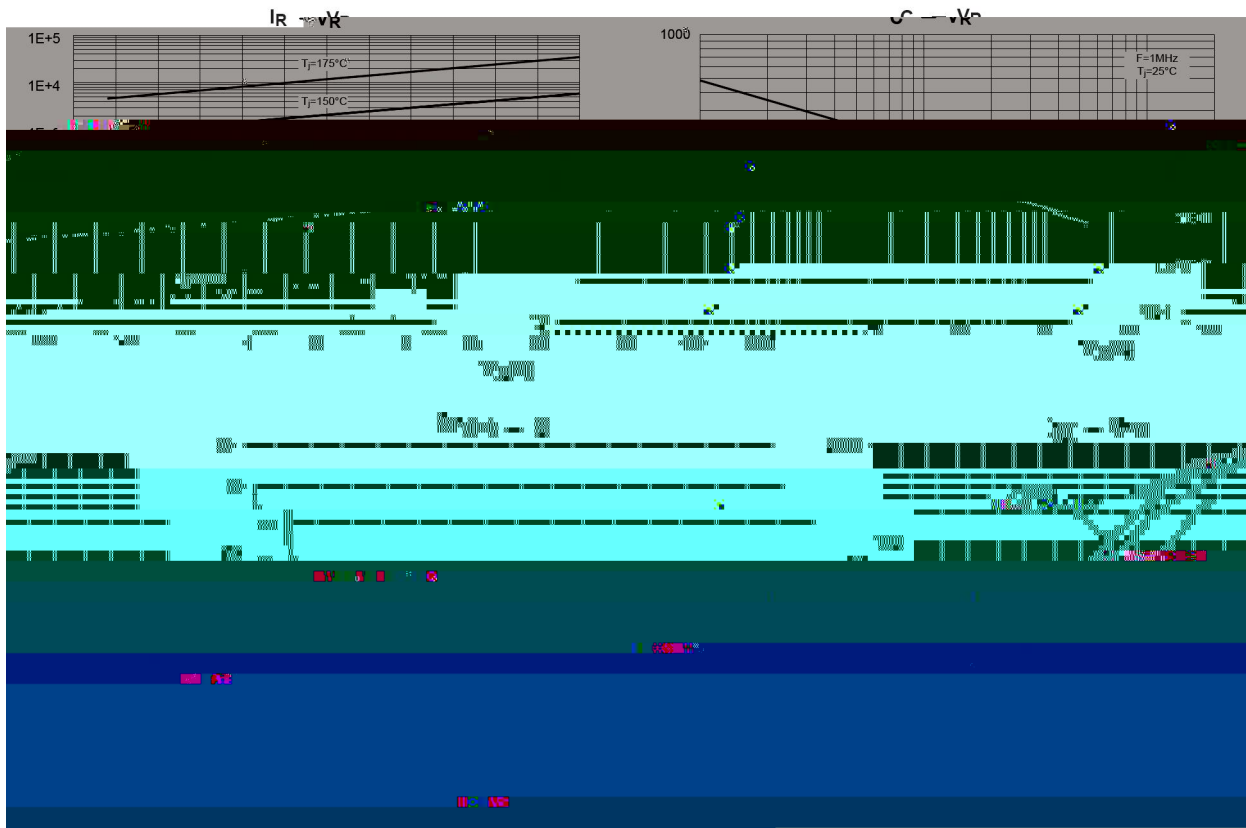
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	150	V
RMS Forward Current	$I_{F(RMS)}$	30	A
Average Forward Current	$I_{F(AV)}$	10	A
Average Forward Current	$I_{F(AV)}$ total device	20	A
Non Repetitive Peak Surge Current	I_{FSM}	180	A
Thermal Resistance Junction to Case	R_{Jc}	1.5	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
Forward Voltage	V_F	$I_F = 10A(T_c = 25^\circ C)$			0.9	V	
		$I_F = 10A(T_c = 125^\circ C)$		0.69	0.75	V	
		$I_F = 20A(T_c = 25^\circ C)$				1.0	V
		$I_F = 20A(T_c = 125^\circ C)$			0.79	0.86	V

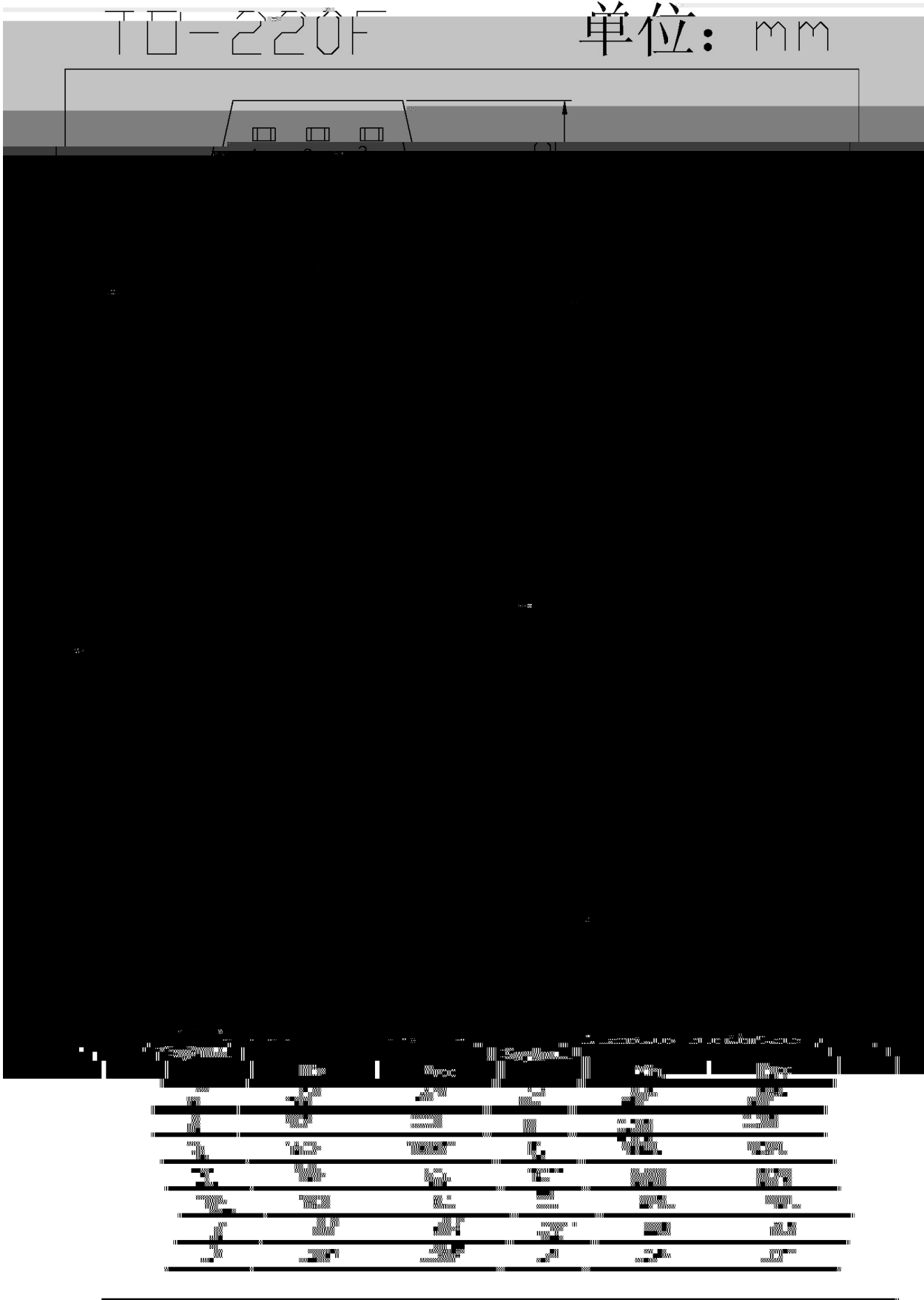
/ Electrical Characteristic Curve



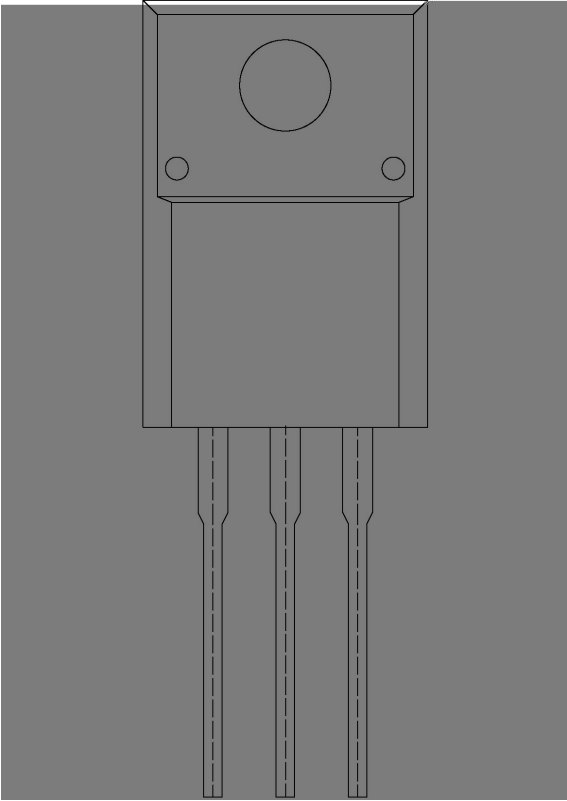
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions

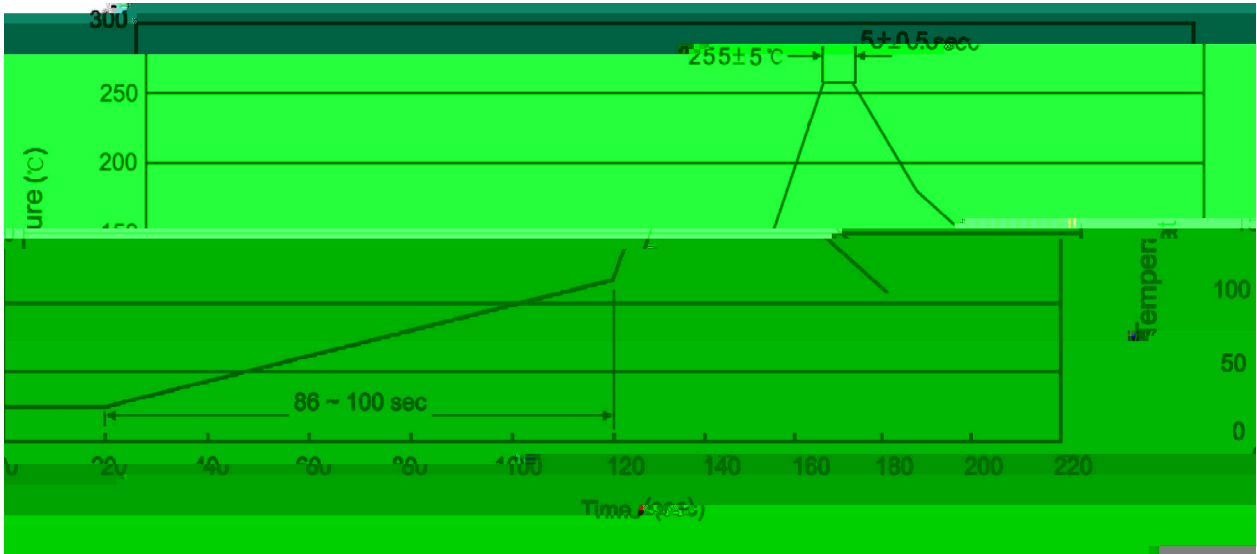


BR
MBRF20150
CT:

Note:

BR: Company Code
MBRF20150: Pr57d05ba6C t , code change with Lot No. 9 TD3.240 Tc8()Tj2

() / Temperature Profile for Dip Soldering(Pb-Free)



- | | | | | | | |
|---|-------|-----|-----------|----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | Note: | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. | |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	_____	Units	_____	Dimension	(unit mm ³)
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